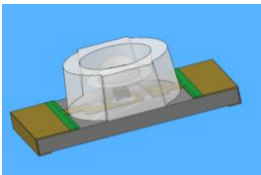


1026 Package Chip LED with Inner Lens

HIR25-21C/L423/2T



Features

- Small double-end package
- Low forward voltage
- Good spectral matching to Si photo detector
- Package in 8mm tape on 7" diameter reel.
- Pb free
- The product itself will remain within RoHS compliant version.
- Compliance with EU REACH
- Compliance Halogen Free .(Br <900 ppm ,Cl <900 ppm , Br+Cl < 1500 ppm).

Descriptions

- HIR25-21C/L423/2T is an infrared emitting diode in miniature SMD package which is molded in a water clear plastic with spherical top view lens.
The device is spectrally matched with silicon photodiode and phototransistor

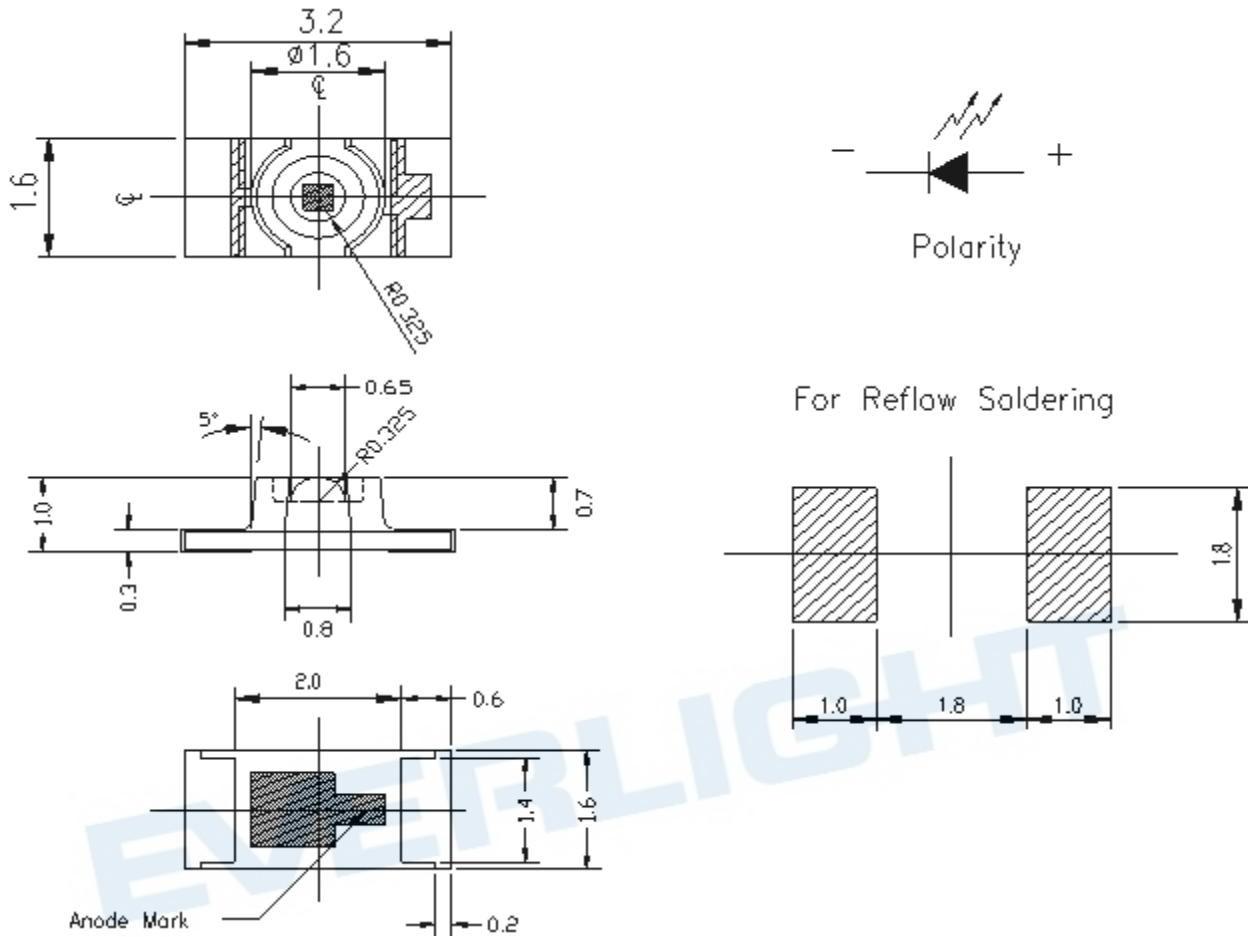
Applications

- PCB mounted infrared sensor
- Infrared remote control units with high power requirement
- Scanner
- Infrared applied system

Device Selection Guide

Part Category	Chip Material	Lens Color
HIR	GaAIAs	Water clear

Package Dimensions



- Notes:**
- 1.All dimensions are in millimeters
 - 2.Tolerances unless dimensions ± 0.1 mm
 - 3.Suggested pad dimension is just for reference only
.Please modify the pad dimension based on individual need

Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Rating	Units
Continuous Forward Current	I _F	50	mA
Peak Forward Current(300pps,10us pulse)	I _{FP}	800	mA
Reverse Voltage	V _R	5.0	V
Operating Junction Temperature	T _j	105	°C
Operating Temperature	T _{opr}	-40 ~ +85	°C
Storage Temperature	T _{stg}	-40 ~ +85	°C
Soldering Temperature	T _{sol}	260	°C
Total Power Dissipation	P _t	100	mW
Power Dissipation at(or below) 25°C Free Air Temperature	P _d	110	mW

Electro-Optical Characteristics (Ta=25°C)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Units
Radiant Intensity	I _e	I _F =20mA	3.0	5.5	9.0	mW/sr
Peak Wavelength	λ _p	I _F =20mA	--	850	--	nm
Spectral Bandwidth	Δλ	I _F =20mA	--	42	--	nm
Forward Voltage	V _F	I _F =50mA	1.30	1.60	2.00	V
Reverse Current	I _R	V _R =5V	--	--	10	μA
Optical rise and fall time	t _r /t _f	I _F =20mA	--	25/15	35/35	ns
View Angle	2θ _{1/2}	I _F =20mA	--	70	--	deg

Typical Electro-Optical Characteristics Curves

Fig.1 Forward Current vs.

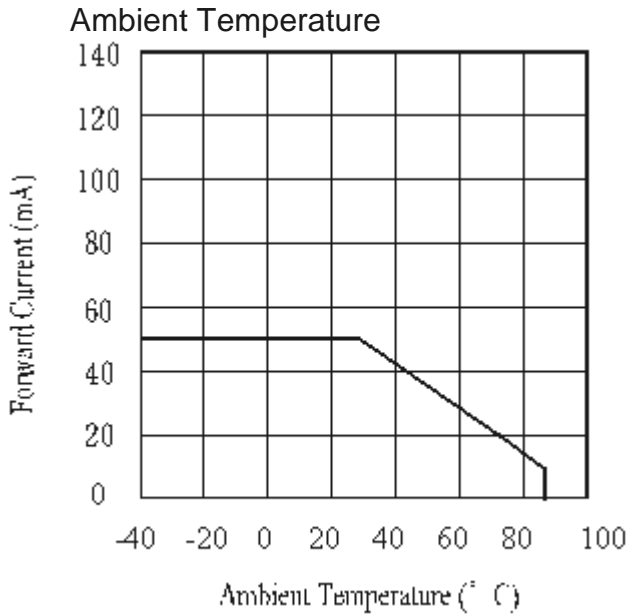


Fig.2 Spectral Distribution

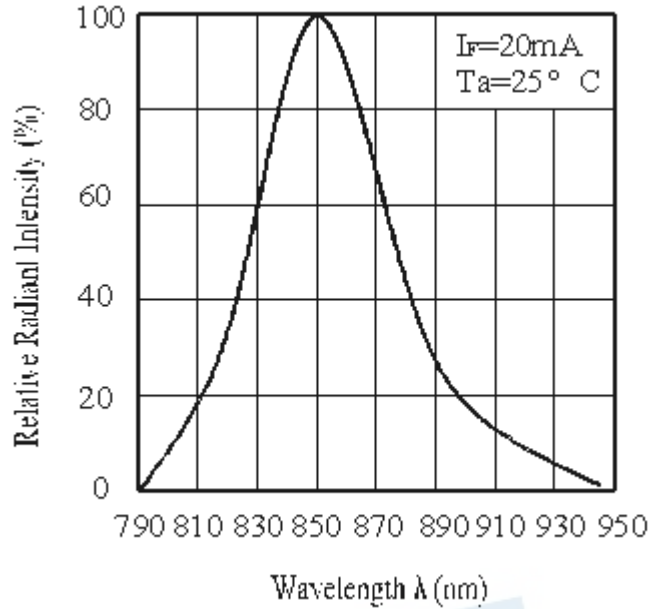


Fig.3 Forward Current vs. Forward Voltage

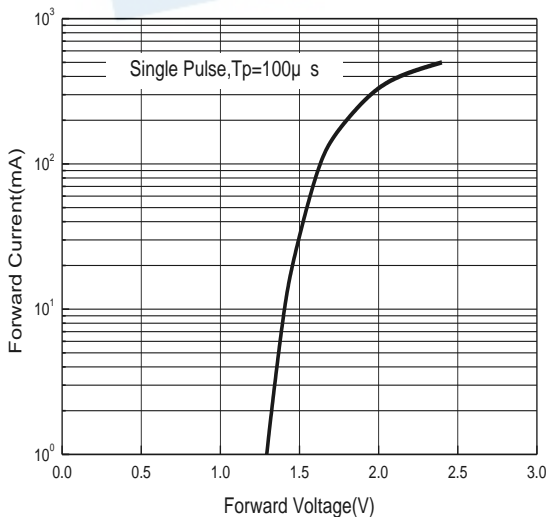
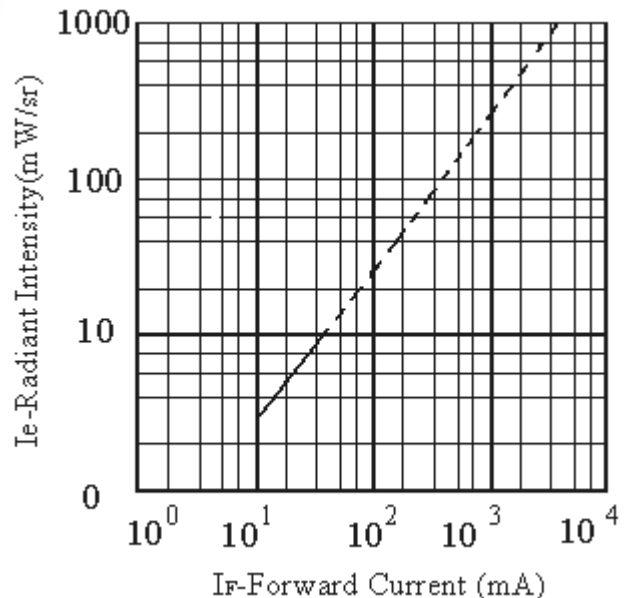
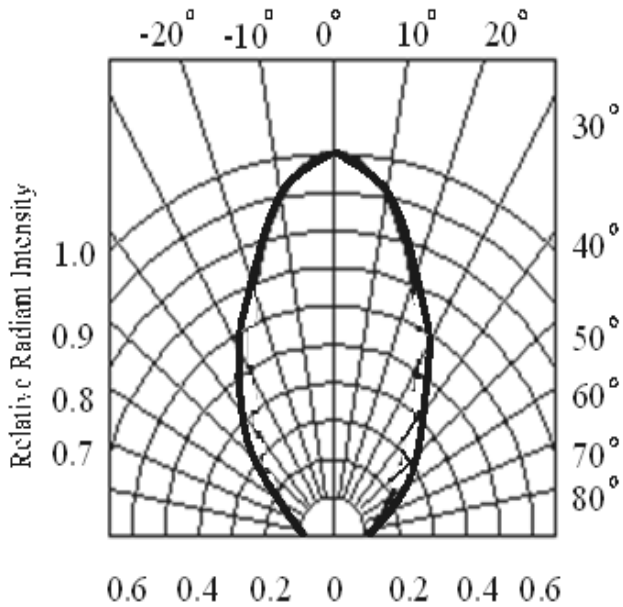


Fig.5 Radiant Intensity vs. Forward Current



Typical Electro-Optical Characteristics Curves

Fig.6 Relative Radiant Intensity vs.
Angular Displacement



Precautions For Use

1. Over-current-proof

Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen).

2. Storage

2.1 Do not open moisture proof bag before the products are ready to use.

2.2 Before opening the package, the Phototransistor should be kept at 10°C~30°C and 90%RH or less.

2.3 The Phototransistor suggested be used within one year.

2.4 After opening the package, the devices must be stored at 10°C~30°C and $\leq 60\%RH$, and used within 168 hours (floor life). If unused Phototransistor remain, it should be stored in moisture proof packages.

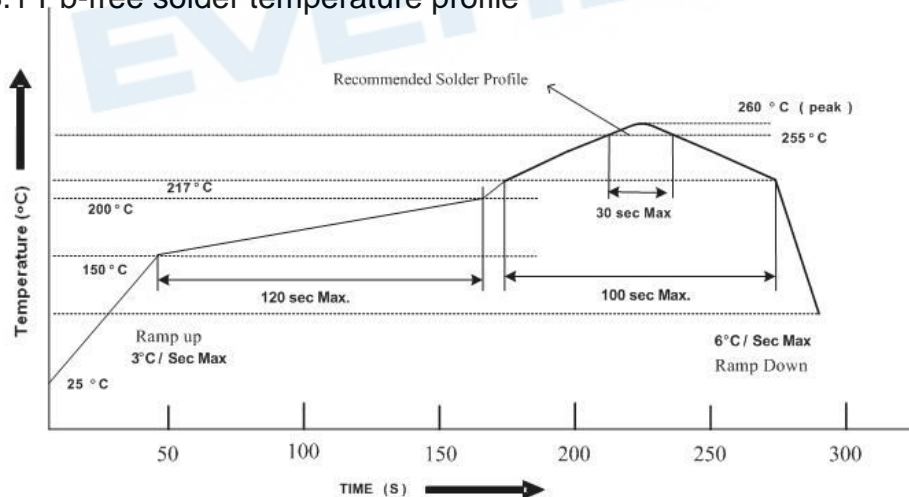
2.5 If the moisture absorbent material (desiccant material) has faded or unopened bag has exceeded the shelf life or devices (out of bag) have exceeded the floor life, baking treatment is required.

2.6 If baking is required, refer to IPC/JEDEC J-STD-033 for bake procedure or recommend the following conditions:

96 hours at 60°C \pm 5°C and < 5 % RH (reeled/tubed/loose units)

3. Soldering Condition

3.1 Pb-free solder temperature profile



3.2 Reflow soldering should not be done more than two times.

3.3 When soldering, do not put stress on the LEDs during heating.

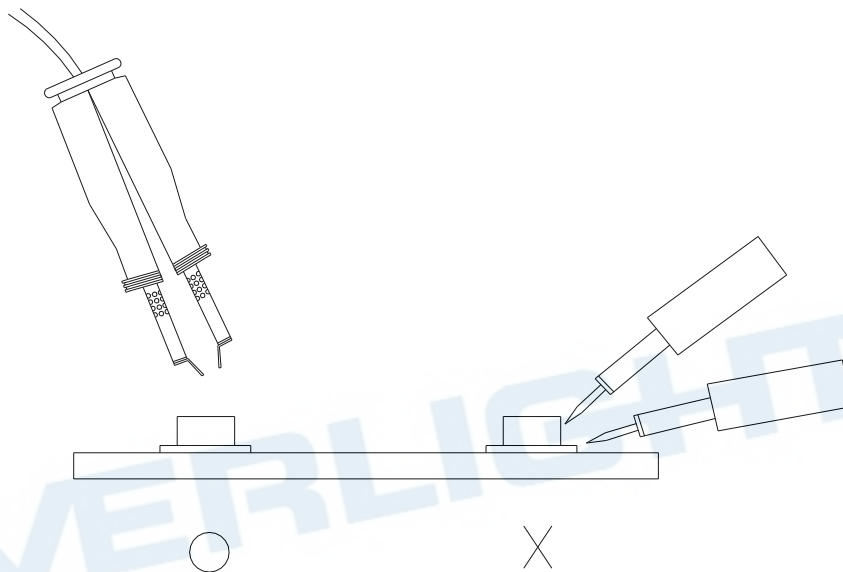
3.4 After soldering, do not warp the circuit board.

4.Soldering Iron

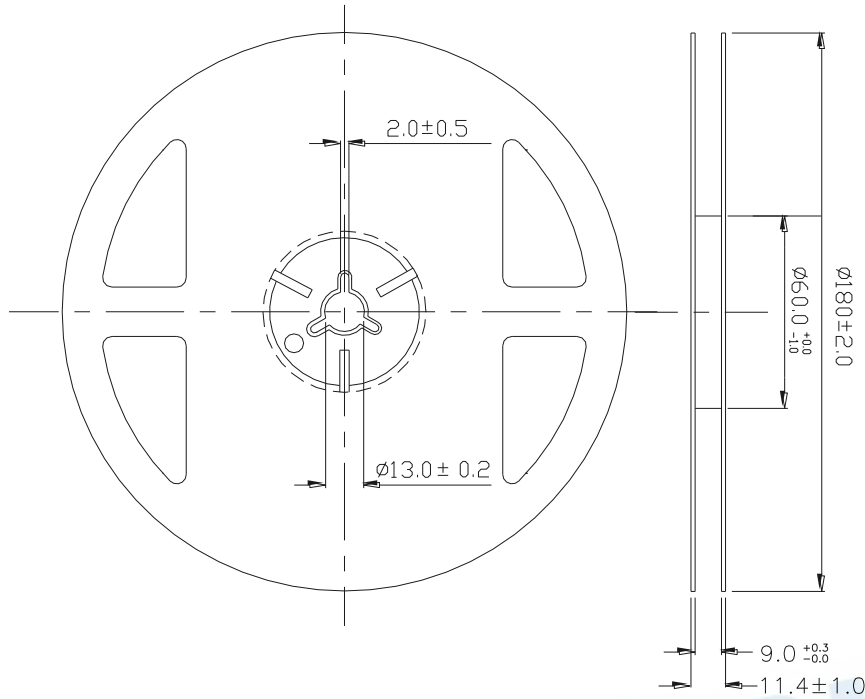
Each terminal is to go to the tip of soldering iron temperature less than 350°C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

5.Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.

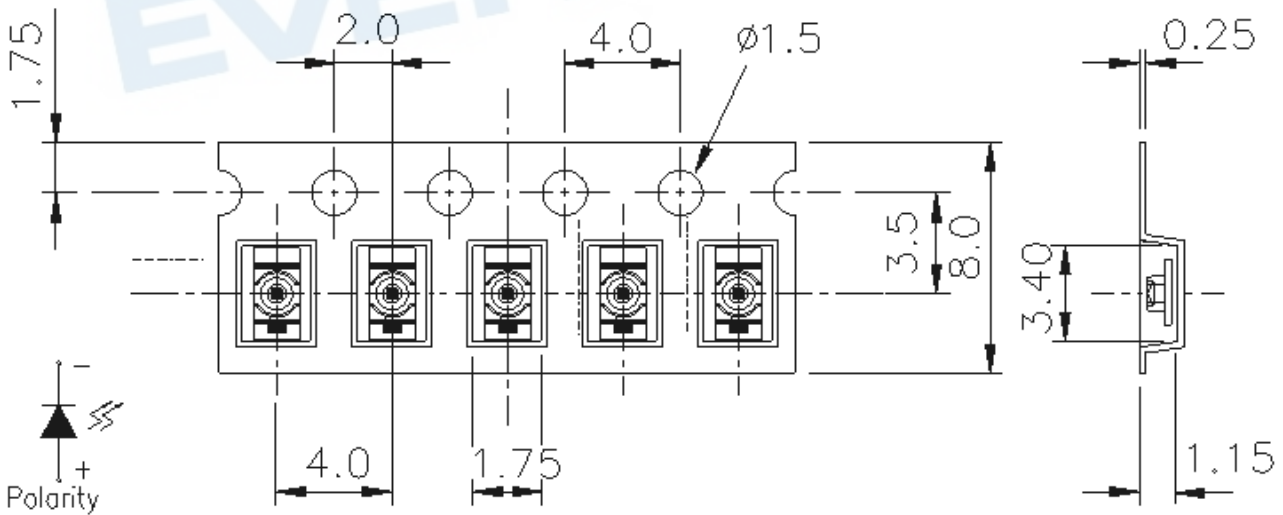


Package Dimensions



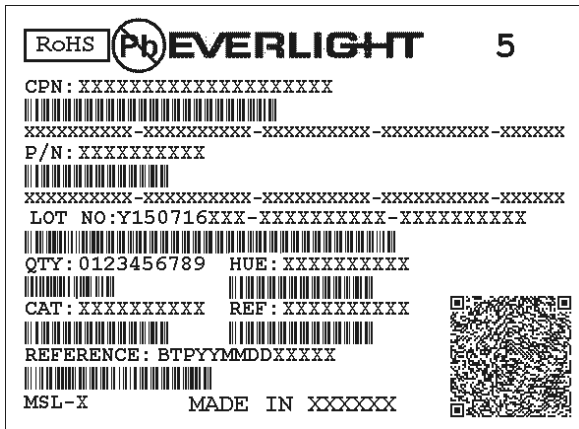
Carrier Tape Dimensions: Loaded quantity 2000 PCS per reel

Progressive direction



Note: The tolerances unless mentioned is ± 0.1 mm ,Unit = mm

Label Form Specification



CPN: Customer's Production Number
P/N : Production Number
LOT No: Lot Number
QTY: Packing Quantity
HUE: Peak Wavelength
CAT: Ranks
REF: Reference
MSL-X: MSL Level
Made In: Manufacture place

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2. The product meets EVERLIGHT published specification for a period of twelve (12) months from date of shipment.
3. The graphs shown in this datasheet are representing typical data only and do not show guaranteed values.
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